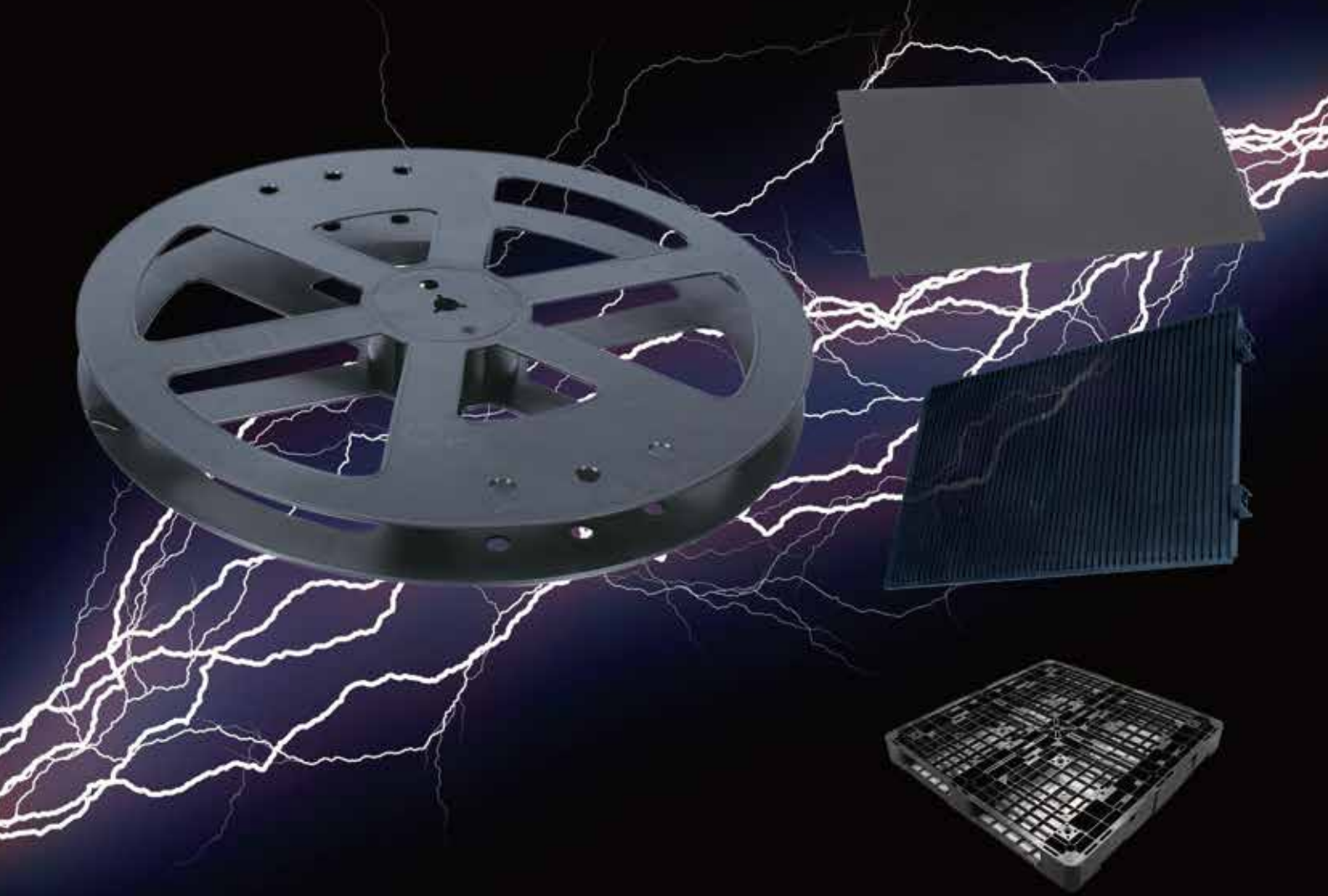




Conductive & Static Dissipative Compounds 导电和抗静电改性塑料

Electroblend® compound is our company's range of conductive compound (antistatic, statically dissipative, conductive and EMI shielding) by incorporating conductive particulate and/or fiber into the host resin to form a conductive matrix. Electrostatic Discharge (ESD) happens when a insulative surface is rubbed against another and the contacted surface are then parted. (ESD) can damage sensitive electronic components, erase magnetic media and set off explosion in highly flammable environment. Electroblend® static dissipative compound is a great solution to all these dangers by effectively dissipate charges before it gets above dangerous level. CIPC's Electroblend® compound can be tailored to offer full spectrum of electrical properties from 10^1 ohm/sq to 10^{12} ohm/sq.

Electroblend® 是公司的导电系列改性塑料，我们使用不同的导电添加剂或填料，如炭黑粉末、碳纤维、金属纤维和金属粉末以达到抗静电、静电消散、导电和电磁波干扰(EMI)屏蔽的功能。

当两个绝缘表面互相接触和摩擦之后突然分开，静电放电(ESD)就会产生。静电放电(ESD)足以摧毁敏感的电子元件，会消除或改变有磁性的介质，在易燃的环境中还有可能会产生爆炸。Electroblend® 导电材料能在电荷累积到危险程度之前就会将它释放掉。CIPC 的 Electroblend® 改性塑料可为客户提供一系列的电阻率在 10^1 到 10^{12} 欧姆/平方之间。

特点：抗静电，导电，刚性好，加工性佳，密度较低，设计自由，低成本。
应用：IC 晶片盘，IC 夹，PCB 板储存盘，抗静电工业容器。

Electroblend® Carbon Fiber, Conductive Carbon Black Filled Series

	TYPICAL PROPERTIES	ASTM TEST METHOD	UNITS	ABS-1800	ABS-1801	ABS-1802	ABS-1804	ABS-1900	ABS-2800	ABS-3900A	ABS-4900	HIPS-1800	HIPS-1802	HIPS-1850	HIPS-4900
				Conductive	Conductive	Conductive	Conductive	Antistatic	Conductive	Antistatic	Antistatic	Conductive	Conductive	Conductive	Antistatic
	Filler Content (灰份)			-	-	-	-	-	15	-	-	-	-	-	-
	MECHANICAL / 机械性能														
1	Tensile Strength / 拉伸强度	D638	MPa	48	40	50	42	42	75	27	47	25	24	18	28
2	Elongation at break / 断裂伸长率	D638	%	3	5.5	6.4	3	5.5	1	70	>10	1.4	15	10	60
3	Flexural Strength / 弯曲强度	D790	MPa	70	63	78	67	65	100	43	74	40	38	30	42
4	Flexural Modulus / 弯曲模数	D790	MPa	3050	2547	3240	3006	2510	8303	1400	2210	2324	2150	1617	2150
5	Notched Izod Impact Strength @ 23°C, 3.2mm Thickness 缺口冲击强度	D256	J/m	35	53	35	37	61	85	500	200	70	85	85	105
	PHYSICAL / 物理性能														
1	Specific Gravity / 比重	D792	g/cm3	1.14	1.11	1.12	1.14	1.10	1.10	1.06	1.06	1.04	1.14	1.16	1.04
2	Mold Shrinkage* / 成型收缩率	D955	%	0.5-0.9	0.5-0.9	0.5-0.9	0.5-0.9	0.5-0.9	0.1-0.2	0.5-0.9	0.5-0.9	0.4-0.6	0.4-0.8	0.4-0.6	0.4-0.7
	THERMAL / 热性能														
1	Heat Deflection Temp@0.45 MPa (66psi) Heat Deflection Temp@1.82 MPa (264psi) 热变形温度	D648 D648	°C °C	- 82	- 83	97 -	- 86	- 83	115 95	90 -	- 87	- 77	- 74	80 70	- 80
2	Flammability / 燃烧性能	UL 94	-	HB	HB	HB	HB	HB	HB	HB	HB	HB	HB	HB	HB
3	Surface Resistivity / 表面电阻率	D257	Ω/cm2	10E3-5	10E3-5	10E3-5	10E3-5	10E6-8	10E3-5	10E9	10E9-11	10E3-5	10E3-5	10E3-5	10E9-11
	SUGGESTED PROCESSING PARAMETERS 建议操作参数														
1	Drying Temperature / 干燥温度		°C	80-90	90	90	90	80-90	80-90	90	90	80	80	80	80
2	Drying Time / 干燥时间		Hours	4	4	4	4	4	4	2-4	2-4	2	2	2-4	2
3	Processing (Melt) Temperature / 操作温度		°C	220-250	220-230	220-230	220-240	220-250	230-250	220-240	220-240	200-230	200-230	200-250	200-230
4	Mold Temperature / 模温		°C	70-80	80-90	80-90	70-80	70-80	70-80	70-80	70-80	60	60	60	60

Applications:

Electroblend® compounds are used in IC trays, business machine components, tweezer, PCB board storage rack etc.

*The mold shrinkage values herein are solely based on our own laboratory testing specimens. Users are strongly advised to conduct their own test as molding conditions, mold design, thickness all play a part in determining the part shrinkage.

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Colour Image Plastic Compound Sdn. Bhd. (Co.No. 527104-T)

HQ - Plant 1: PT 59218, Jalan Balakong Jaya, Taman Perindustrian Balakong Jaya, 43300 Seri Kembangan, Selangor, Malaysia. Telephone : +603 - 89382496, +603 - 89382870, +603 - 89382790 Fax : +603 - 89403088

Plant 2 : Lot 557 (GM 340), Mukim Hulu Semenyih, Daerah Hulu Langat, Selangor Darul Ehsan, Malaysia.

Johor Sales/ Technical office : CK Tan (Marketing & Technical Executive) Mobile : +6012 - 2127306 Email : ck.tan_mktg@cipresin.com

Business Contact : Lawrence Ong (Executive Director) Mobile : +6012 - 2235891 Email : lawrence.ong@cipresin.com / Tatsuo Fujita (Japanese Sales Advisor) Mobile : +6012 -2235891 Email : fujita@cipresin.com / Linus Cheong Yong Sheng (Marketing Executive) Mobile : +6012 - 2270912 Email : yscheong_mktg@cipresin.com / Yong Yao Sheng (Marketing Executive) Mobile : +6017 - 2985292 Email : yaosheng_mktg@cipresin.com

Electroblend® Carbon Fiber, Conductive Carbon Black Filled Series

	TYPICAL PROPERTIES	ASTM TEST METHOD	UNITS	PP-1800	PP-1804	PP-1805	PP-1806	PP-1900	PP-1901	PP-1902	PC-2801	PBT-1801	PBT-1901	PBT-2800
				Conductive	Conductive	Conductive	Conductive	Antistatic	Dissipative	Dissipative	Conductive	Conductive	Antistatic	Conductive
	Filler Content (灰份)			-	-	-	-	-	-	-	10	20	20	30
	MECHANICAL / 机械性能													
1	Tensile Strength / 拉伸强度	D638	MPa	20	25	30	25	28	24	24	113	70	85	130
2	Elongation at break / 断裂伸长率	D638	%	30	4	35	>20	55	40	40	3.3	2	2.5	2
3	Flexural Strength / 弯曲强度	D790	MPa	25	41	47	35	40	43	40	178	115	110	190
4	Flexural Modulus / 弯曲模数	D790	MPa	800	1230	1550	1100	1145	1450	1400	8830	6650	7200	10710
5	Notched Izod Impact Strength @ 23°C, 3.2mm Thickness 缺口冲击强度	D256	J/m	550	132	480	680	500	600	650	80	50	75	142
	PHYSICAL / 物理性能													
1	Specific Gravity / 比重	D792	g/cm3	1.00	1.03	1.03	1.01	1.00	1.00	1.00	1.27	1.51	1.51	1.46
2	Mold Shrinkage* / 成型收缩率	D955	%	1.2-1.4	1.2-1.4	1.2-1.4	1.2-1.5	1.2-1.4	1.2-1.5	1.2-1.5	0.1-0.3	0.2-0.6	0.2-0.6	0.4-0.6
	THERMAL / 热性能													
1	Heat Deflection Temp@0.45 MPa (66psi) Heat Deflection Temp@1.82 MPa (264psi) 热变形温度	D648 D648	°C °C	77 -	- 65	110 -	95 -	98 -	95 -	95 -	- 143	- -	- -	- 212
2	Flammability / 燃烧性能	UL 94	-	HB	HB	HB	HB	HB	HB	HB	V0	HB	HB	HB
3	Surface Resistivity / 表面电阻率	D257	Ω/cm2	10E3-5	10E3-5	10E3-5	10E3-5	10E6-7	10E6-8	10E7-9	10E3-5	10E3-5	10E6-8	10E3-5
	SUGGESTED PROCESSING PARAMETERS 建议操作参数													
1	Drying Temperature / 干燥温度		°C	80	80	80	80	80	80	80	90	120	120	120
2	Drying Time / 干燥时间		Hours	4	4	4	2-4	4	2-4	2-4	4	4	4	4
3	Processing (Melt) Temperature / 操作温度		°C	190-220	190-220	190-220	190-220	190-220	190-220	190-220	260-290	240-260	240-260	240-260
4	Mold Temperature / 模温		°C	60	60	60	60-90	60	60-90	60-90	85-110	80-100	80-100	80-100

Applications:

Electroblend® compounds are used in IC trays, business machine components, tweezer, PCB board storage rack etc.

*The mold shrinkage values herein are solely based on our own laboratory testing specimens. Users are strongly advised to conduct their own test as molding conditions, mold design, thickness all play a part in determining the part shrinkage.

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